

DERWENT-ACC-NO: 1998-128121

DERWENT-WEEK: 200020

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TITLE: Device for removing marking of a semiconductor chip  
package and method of removing marking using the said  
device - NoAbstract

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PATENT-ASSIGNEE: SAMSUNG ELECTRONICS CO LTD[SMSU]

PRIORITY-DATA: 1995KR-0022124 (July 25, 1995)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	
MAIN-IPC				
<u>KR 97008549 A</u>	February 24, 1997	N/A	000	H01L
023/544				
KR 148079 B1	August 1, 1998	N/A	000	H01L
023/544				

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
KR 97008549A	N/A	1995KR-0022124	July 25, 1995
KR 148079B1	N/A	1995KR-0022124	July 25, 1995

INT-CL (IPC): H01L023/00, H01L023/544

ABSTRACTED-PUB-NO: KR 97008549A

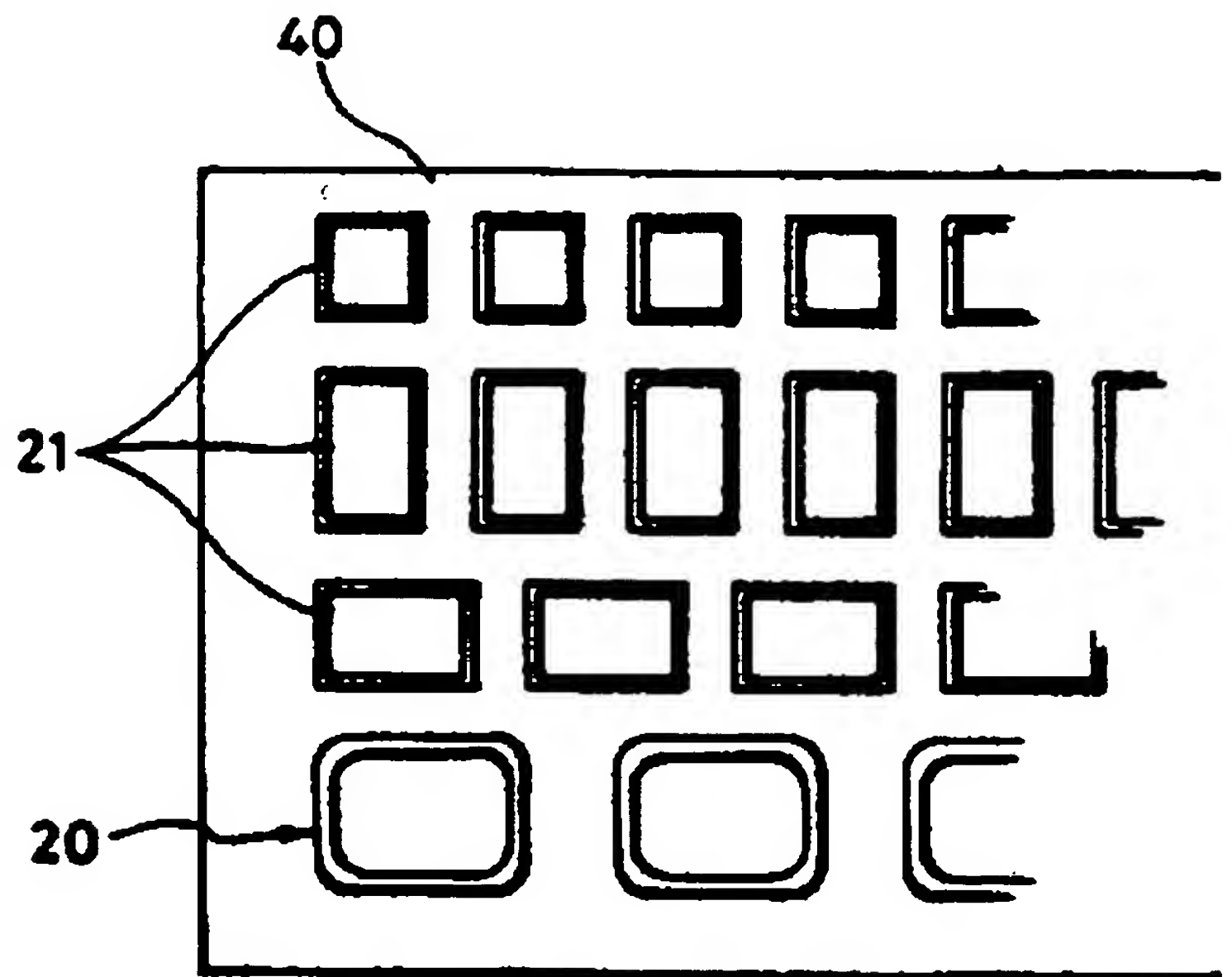
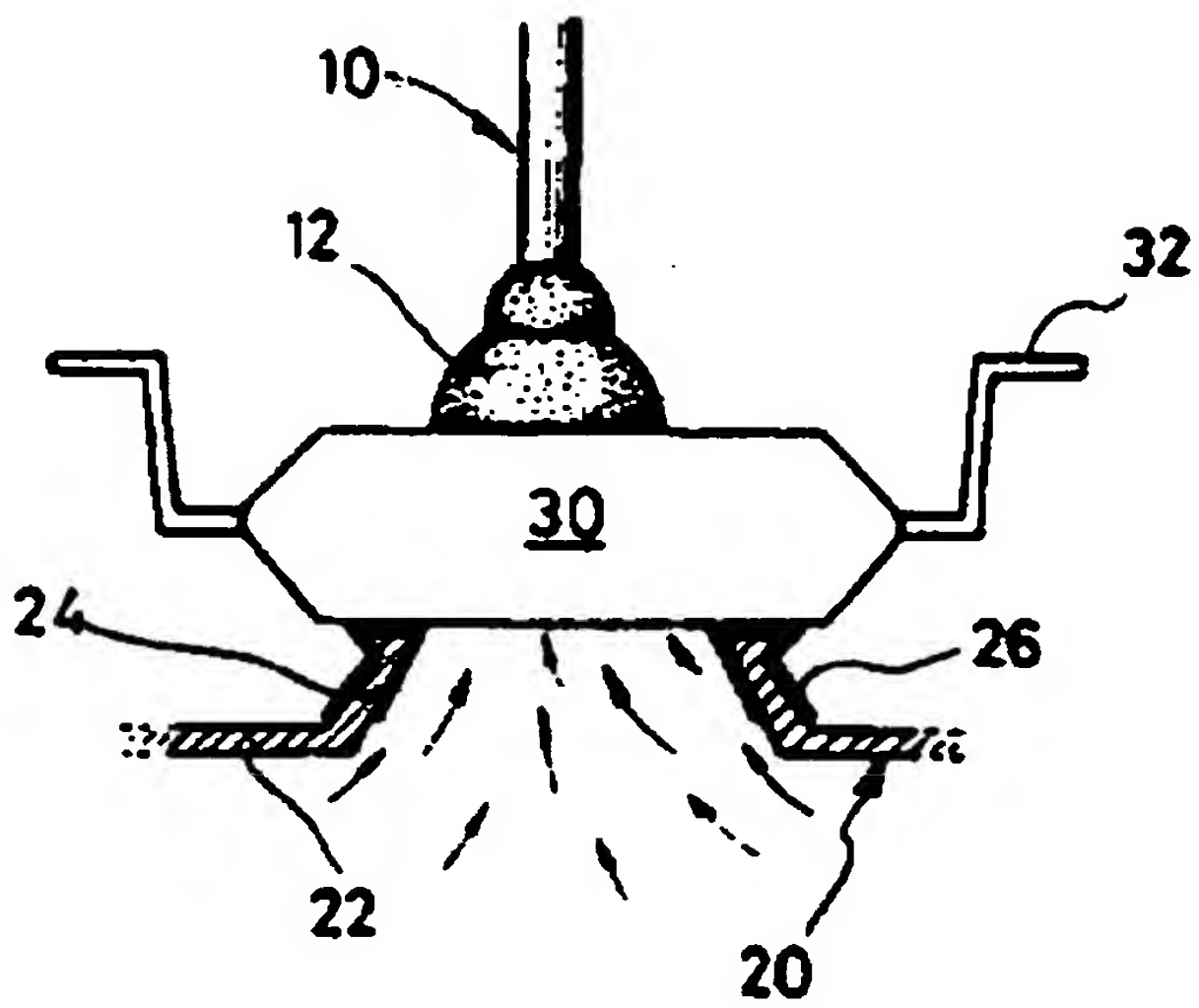
EQUIVALENT-ABSTRACTS:

CHOSEN-DRAWING: Dwg.1

TITLE-TERMS: DEVICE REMOVE MARK SEMICONDUCTOR CHIP PACKAGE METHOD REMOVE MARK  
DEVICE NOABSTRACT

DERWENT-CLASS: U11

EPI-CODES: U11-E02B3;



*ordered  
patent  
from  
web*